WORKPIECE PROCESSING DEVICE

ABSTRACT OF THE DISCLOSURE

A workpiece processing device (10) for processing a workpiece (60; 20, 36) comprises: a surface protection film peeling means (50) for peeling a surface protection film (110), which is adhered to a front surface (21) of a workpiece, with a peeling tape (4); a bar code adhering means (11) for adhering a bar code (65) corresponding to the workpiece to the workpiece; and a movable support table (72) for supporting the workpiece. A peeling operation for peeling the surface protection film conducted by the surface protection film peeling means and a adhering operation for adhering a bar code conducted by the bar code adhering means are given to the workpiece while the workpiece is being supported by the support table. Due to the foregoing, it is possible to avoid failures when adhering the bar code to the workpiece, such as a wafer. The bar code adhering means may adhere the bar code, which corresponds to character information of the workpiece read out by an optical reading means, to the workpiece.

Fig. 3